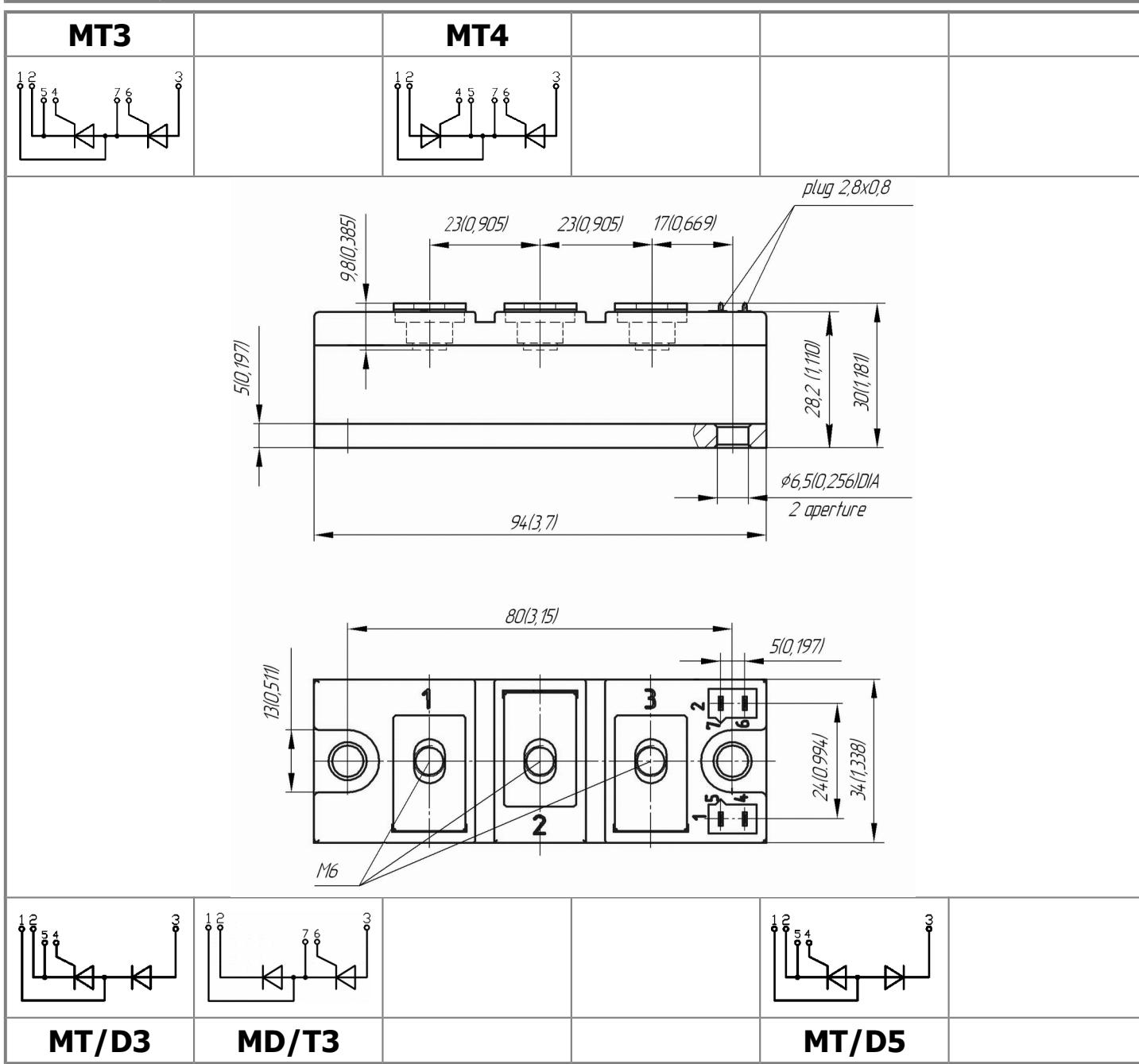




Electrically isolated base plate
Industrial standard package
Simplified mechanical design, rapid assembly
Pressure contact

**Double Thyristor Module
For Phase Control
MTx-130-28-F**

Mean on-state current	I _{TAV}	130 A	
Repetitive peak off-state voltage	V _{DRM}	2400 ÷ 2800 V	
Repetitive peak reverse voltage	V _{RRM}		
Turn-off time	t _q	250 μ s	
V _{DRM} , V _{RRM} , V	2400	2600	2800
Voltage code	24	26	28
T _j , °C	- 40 ÷ 125		



MAXIMUM ALLOWABLE RATINGS

Symbols and parameters		Units	Values	Test conditions	
ON-STATE					
I_{TAV}	Mean on-state current	A	130	$T_c = 85^\circ C$;	
I_{TRMS}	RMS on-state current	A	204	180° half-sine wave; 50 Hz	
I_{TSM}	Surge on-state current	kA	3.4 4.0	$T_j = T_{j \max}$ $T_j = 25^\circ C$	180° half-sine wave; $t_p = 10$ ms; single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μs ; $di_G/dt \geq 1$ A/ μs
			4.0 4.6	$T_j = T_{j \max}$ $T_j = 25^\circ C$	180° half-sine wave; $t_p = 8.3$ ms; single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μs ; $di_G/dt \geq 1$ A/ μs
I^2t	Safety factor	$A^2 \cdot 10^3$	55 75	$T_j = T_{j \max}$ $T_j = 25^\circ C$	180° half-sine wave; $t_p = 10$ ms; single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μs ; $di_G/dt \geq 1$ A/ μs
			65 85	$T_j = T_{j \max}$ $T_j = 25^\circ C$	180° half-sine wave; $t_p = 8.3$ ms; single pulse; $V_D = V_R = 0$ V; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μs ; $di_G/dt \geq 1$ A/ μs
BLOCKING					
V_{DRM}, V_{RRM}	Repetitive peak off-state and Repetitive peak reverse voltages	V	2400÷2800	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; 50 Hz; Gate open	
V_{DSM}, V_{RSM}	Non-repetitive peak off-state and Non-repetitive peak reverse voltages	V	2500÷2900	$T_{j \min} < T_j < T_{j \max}$; 180° half-sine wave; single pulse; Gate open	
V_D, V_R	Direct off-state and Direct reverse voltages	V	$0.75 \cdot V_{DRM}$ $0.75 \cdot V_{RRM}$	$T_j = T_{j \max}$; Gate open	
TRIGGERING					
I_{FGM}	Peak forward gate current	A	5	$T_j = T_{j \max}$	
V_{RGM}	Peak reverse gate voltage	V	5		
P_G	Gate power dissipation	W	3	$T_j = T_{j \max}$ for DC gate current	
SWITCHING					
$(di_T/dt)_{crit}$	Critical rate of rise of on-state current non-repetitive ($f=1$ Hz)	$A/\mu s$	200	$T_j = T_{j \max}$; $V_D = 0.67 \cdot V_{DRM}$; $I_{TM} = 2 I_{TAV}$; Gate pulse: $I_G = 2$ A; $t_{GP} = 50$ μs ; $di_G/dt \geq 2$ A/ μs	
THERMAL					
T_{stg}	Storage temperature	°C	-40 ÷ 50		
T_j	Operating junction temperature	°C	-40 ÷ 125		
MECHANICAL					
a	Acceleration under vibration	m/s^2	50		

CHARACTERISTICS

Symbols and parameters		Units	Values	Conditions	
ON-STATE					
V _{TM}	Peak on-state voltage, max	V	1.80	T _j =25 °C; I _{TM} = 500 A	
V _{T(TO)}	On-state threshold voltage, max	V	0.85	T _j =T _j max;	
r _T	On-state slope resistance, max	mΩ	2.400	0.5 π I _{TAV} < I _T < 1.5 π I _{TAV}	
I _L	Latching current, max	mA	500	T _j =25 °C; V _D =12 V; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥1 A/μs	
I _H	Holding current, max	mA	250	T _j =25 °C; V _D =12 V; Gate open	
BLOCKING					
I _{DRM} , I _{RRM}	Repetitive peak off-state and Repetitive peak reverse currents, max	mA	40	T _j =T _j max; V _D =V _{DRM} ; V _R =V _{RRM}	
(dv _D /dt) _{crit}	Critical rate of rise of off-state voltage, min	V/μs	1000	T _j =T _j max; V _D =0.67·V _{DRM} ; Gate open	
TRIGGERING					
V _{GT}	Gate trigger direct voltage, max	V	4.00 2.50 2.00	T _j = T _j min T _j =25 °C T _j = T _j max	V _D =12 V; I _D =3 A; Direct gate current
I _{GT}	Gate trigger direct current, max	mA	400 250 200	T _j = T _j min T _j = 25 °C T _j = T _j max	
V _{GD}	Gate non-trigger direct voltage, min	V	0.25	T _j =T _j max; V _D =0.67·V _{DRM} ;	Direct gate current
I _{GD}	Gate non-trigger direct current, min	mA	10.00	Direct gate current	
SWITCHING					
t _{gd}	Delay time	μs	2.50	T _j =25 °C; V _D =0.4·V _{DRM} ; I _{TM} =I _{TAV} ; Gate pulse: I _G =2 A; t _{GP} =50 μs; di _G /dt≥2 A/μs	
t _q	Turn-off time, max	μs	250	dv _D /dt=50 V/μs; T _j =T _j max; I _{TM} =200 A; di _R /dt=-10 A/μs; V _R =100V; V _D =0.67 V _{DRM} ;	
THERMAL					
R _{thjc}	Thermal resistance, junction to case				
	per module	°C/W	0.0950	180° half-sine wave, 50 Hz	
	per arm	°C/W	0.1900		
	per module	°C/W	0.0900		
	per arm	°C/W	0.1800	DC	
R _{thch}	Thermal resistance, case to heatsink				
	per module	°C/W	0.0300		
	per arm	°C/W	0.0600		
INSULATION					
V _{ISOL}	Insulation test voltage	kV	3.00	Sine wave, 50 Hz;	
			3.60	RMS t=1 sec	
MECHANICAL					
M ₁	Mounting torque (M6) ¹⁾	Nm	6.00	Tolerance ± 15%	
M ₂	Terminal connection torque (M6) ¹⁾	Nm	6.00	Tolerance ± 15%	
w	Weight	g	320		

PART NUMBERING GUIDE								NOTES
MT 3 - 130 - 28 - F - N 1 2 3 4 5 6								¹⁾ The screws must be lubricated
1. Thyristor module (MT) Thyristor – Diode module (MT/D) Diode – Thyristor module (MD/T) 2. Circuit Schematic 3. Average On-state Current, A 4. Voltage Code 5. Package Type (M.F) 6. Ambient Conditions: N – Normal								



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